

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.56952	100.0	6.1
Subtotal				0.56952	100	6.1
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03744	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01123	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03744	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.35303	99.77	400.0777
Subtotal				37.43914	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.83678	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.90997	10.0	63.3
	Filler	Silica fused	60676-86-0	50.23473	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.1182	0.2	1.266
Subtotal				59.09968	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.33411	100.0	25
Subtotal				2.33411	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03564	100.0	0.3817
	Pure metal	Aluminium (Al)	7429-90-5	0.21847	100.0	2.34
Subtotal				0.25411	200	2.7217
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00607	2.0	0.065
	Lead alloy	Silver (Ag)	7440-22-4	0.00759	2.5	0.08125
	Lead alloy	Lead (Pb)	7439-92-1	0.28978	95.5	3.10375
Subtotal				0.30344	100	3.25
Total				100	100	1071.0717

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